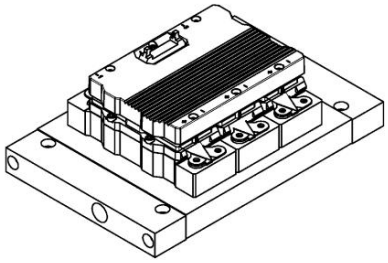
SKiiP 803GD061-3DUW ...



SKiiP® 3

6-pack-integrated intelligent power system

Power section

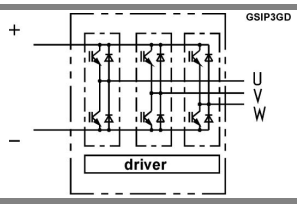
SKiiP 803GD061-3DUW

Preliminary Data

Features

- SKiiP technology inside
- Low loss IGBTs
- CAL diode technology
- Integrated current sensor
- Integrated temperature sensor
- Integrated heat sink
- IEC 60721-3-3 (humidity) class 3K3/IE32 (SKiiP® 3 System)
- IEC 68T.1 (climate) 40/125/56 (SKiiP® 3 power section)
- UL recognized File no. E63532 (SKiiP® 3 power section)

1) with assembly of suitable MKP capacitor per terminal (SEMIKRON type is recommended)



Case S33

Absolute Maximum Ratings		T_s = 25°C unless otherwise specified	
Symbol	**Conditions**	**Values**	**Units**
IGBT			
V_{CES}		600	V
V_{CC} 1)	Operating DC link voltage	400	V
V_{GES}		± 20	V
I_C	T_s = 25 (70) °C	800 (600)	A
Inverse diode			
I_F = - I_C	T_s = 25 (70) °C	620 (470)	A
I_{FSM}	T_j = 150 °C, t_p = 10 ms; sin	6000	A
I²t (Diode)	Diode, T_j = 150 °C, 10 ms	180	kA²s
T_j, (T_{stg})		- 40 ... + 150 (125)	°C
V_{isol}	rms, AC, 1min	2500	V
$I_{AC\text{-}terminal}$	per AC terminal, rms, T_s = 70 °C, $T_{terminal}$ <115 °C	400	A

Characteristics		T_s = 25°C unless otherwise specified			
Symbol	**Conditions**	**min.**	**typ.**	**max.**	**Units**
IGBT					
V_{CEsat}	I_C = 300 A, T_j = 25 (125) °C; measured at terminal		1,5 (1,6)	1,8	V
V_{CEO}	T_j = 25 (125) °C; at terminal		0,8 (0,7)	1 (0,9)	V
r_{CE}	T_j = 25 (125) °C; at terminal		2,4 (3,1)	2,7 (3,4)	mΩ
I_{CES}	V_{GE} = 0 V, V_{CE} = V_{CES}, T_j = 25 (125) °C		1,2 (36)		mA
E_{on} + E_{off}	I_C = 300 A, V_{CC} = 300 V		27		mJ
	T_j = 125 °C, V_{CC} = 400 V		39		mJ
$R_{CC+EE'}$	terminal chip, T_j = 25 °C		0,5		mΩ
L_{CE}	top, bottom		12		nH
C_{CHC}	per phase, AC-side		1		nF
Inverse diode					
V_F = V_{EC}	I_F = 300 A, T_j = 25 (125) °C measured at terminal		1,3 (1,2)	1,5	V
V_{TO}	T_j = 25 (125) °C		0,8 (0,6)	1 (0,8)	V
r_T	T_j = 25 (125) °C		1,5 (1,9)	1,7 (2)	mΩ
E_{rr}	I_C = 300 A, V_{CC} = 300 V		5		mJ
	T_j = 125 °C, V_{CC} = 400 V		6		mJ
Mechanical data					
M_{dc}	DC terminals, SI Units	6		8	Nm
M_{ac}	AC terminals, SI Units	13		15	Nm
w	SKiiP® 3 System w/o heat sink		2,4		kg
w	heat sink		5,2		kg

Thermal characteristics (NWK 40; 8l/min; 50%glyc.); "s" reference to heat sink; "r" reference to built-in temperature sensor (acc. IEC 60747-15)

$R_{th(j\text{-}s)I}$	per IGBT						0,051	K/W
$R_{th(j\text{-}s)D}$	per diode						0,1	K/W
Z_{th}	R_i (mK/W) (max. values)				tau_i(s)			
	1	2	3	4	1	2	3	4
$Z_{th(j\text{-}r)I}$	4,2	20,4	23,4	0	69	0,35	0,02	1
$Z_{th(j\text{-}r)D}$	7,8	12	53,1	53,1	50	5	0,25	0,04
$Z_{th(r\text{-}a)}$	4,6	4,7	1,1	0,6	48	15	2,8	0,4

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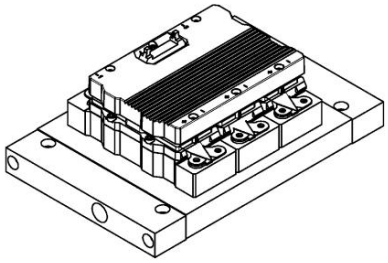

SKiiP® 3

Absolute Maximum Ratings			
Symbol	**Conditions**	**Values**	**Units**
V_{S2}	unstabilized 24 V power supply	30	V
V_i	input signal voltage (high)	15 + 0,3	V
dv/dt	secondary to primary side	75	kV/µs
V_{isolIO}	input / output (AC, rms, 2s)	2500	V
V_{isolPD}	partial discharge extinction voltage, rms, $Q_{PD} \leq 10$ pC;	960	V
V_{isol12}	output 1 / output 2 (AC, rms, 2s)	1500	V
f	switching frequency	20	kHz
T_{op} (T_{stg})	operating / storage temperature	- 40 ... + 85	°C

6-pack-integrated intelligent power system

6-pack
integrated gate driver
SKiiP 803GD061-3DUW

Preliminary Data

Gate driver features

- CMOS compatible inputs
- Wide range power supply
- Integrated circuitry to sense phase current, heat sink temperature and DC-bus voltage (option)
- Short circuit protection
- Over current protection
- Over voltage protection (option)
- Power supply protected against under voltage
- Interlock of top/bottom switch
- Isolation by transformers
- Fibre optic interface (option for GB-types only)
- IEC 68T.1 (climate) 40/85/56 (SKiiP® 3 gate driver)

Characteristics					(T_a = 25°C)
Symbol	**Conditions**	**min.**	**typ.**	**max.**	**Units**
V_{S2}	supply voltage non stabilized	13	24	27	V
I_{S2}	V_{S2} = 24 V		375+30*f/kHz+0,00111*(I_{AC}/A)^2		mA
V_{iT+}	input threshold voltage (High)	11,2			V
V_{iT-}	input threshold voltage (Low)			5,4	V
R_{IN}	input resistance		10		kΩ
C_{IN}	input capacitance		1		nF
$t_{d(on)IO}$	input-output turn-on propagation time		1,1		µs
$t_{d(off)IO}$	input-output turn-off propagation time		1,1		µs
$t_{pERRRESET}$	error memory reset time		9		µs
t_{TD}	top / bottom switch interlock time		3,3		µs
$I_{analogOUT}$	max. 5mA; 8 V corresponds to 15 V supply voltage for external components		600		A
I_{s1out}	max. load current			50	mA
I_{TRIPSC}	over current trip level (I_{analog} OUT = 10 V)		750		A
T_{tp}	over temperature protection	110		120	°C
U_{DCTRIP}	U_{DC}-protection ($U_{analog\ OUT}$ = 9 V); (option for GB types)		400		V

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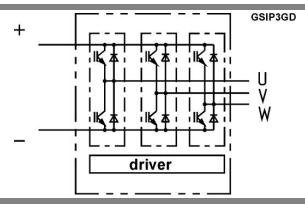

Case S33

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